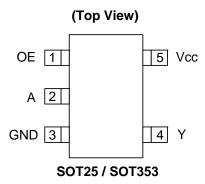


Description

The 74AHC1G126 is a single non-inverting buffer/bus driver with a 3-state output. The output enters a high impedance state when a LOW-level is applied to the output enable (OE) pin. The device is designed for operation with a power supply range of 2.0V to 5.5V.

Pin Assignments



Features

- Supply Voltage Range from 2.0V to 5.5V
- ± 8 mA Output Drive at 5.0V
- CMOS low power consumption
- Schmitt Trigger Action at All Inputs Make the Circuit Tolerant for Slower Input Rise and Fall Time
- ESD Protection per JESD 22
 - o Exceeds 200-V Machine Model (A115-A)
 - o Exceeds 2000-V Human Body Model (A114-A)
 - Exceeds 1000-V Charged Device Model (C101C)
- Latch-Up Exceeds 100mA per JESD 78, Class II
- SOT25 and SOT353: Assembled with "Green" Molding Compound (no Br, Sb)
- Lead Free Finish / RoHS Compliant (Note 1)

Applications

- General Purpose Logic
- Wide array of products such as:
 - o PCs, networking, notebooks, netbooks, PDAs
 - o Computer peripherals, hard drives, CD/DVD ROM
 - o TV, DVD, DVR, set top box
 - Personal Navigation / GPS
 - o MP3 players ,Cameras, Video Recorders

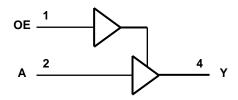
Notes: 1. EU Directive 2002/95/EC (RoHS). All applicable RoHS exemptions applied. Please visit our website at http://www.diodes.com/products/lead_free.html.



Pin Descriptions

Pin Name	Pin NO.	Description	
OE	1	Output Enable	
Α	2	Data Input	
GND	3	Ground	
Y	4	Data Output	
V _{CC}	5	Supply Voltage	

Logic Diagram



Function Table

Inp	Inputs				
OE	Α	Υ			
Н	Н	Н			
Н	L	L			
L	X	Z			



Absolute Maximum Ratings (Note 2)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	KV
ESD CDM	Charged Device Model ESD Protection	1	KV
ESD MM	Machine Model ESD Protection	200	V
V _{CC}	Supply Voltage Range	-0.5 to 6.5	V
VI	Input Voltage Range	-0.5 to 6.5	V
Vo	Voltage applied to output in high or low state	-0.5 to V _{CC} +0.5	V
I _{IK}	Input Clamp Current V _I <0	-20	mA
I _{OK}	Output Clamp Current (V _O < 0 or V _O > V _{CC})	±20	mA
Io	Continuous output current (V _O = 0 to V _{CC})	±25	mA
I _{CC}	Continuous current through V _{CC}	50	mA
I _{GND}	I _{GND} Continuous current through GND		mA
TJ	T _J Operating Junction Temperature		°C
T _{STG}	Storage Temperature	-65 to 150	°C

Notes: 2. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.

Recommended Operating Conditions (Note 3)

Symbol		Parameter	Min	Max	Unit
V_{CC}	Operating Voltage		2	5.5	V
		V _{CC} = 2V	1.5		
V_{IH}	High-level Input Voltage	$V_{CC} = 3V$	2.1		V
	3 2 2 7 2 3 3	$V_{CC} = 5.5V$	3.85		
		$V_{CC} = 2V$		0.5	
V_{IL}	Low-level input voltage	$V_{CC} = 3V$		0.9	V
		$V_{CC} = 5.5V$		1.65	
VI	Input Voltage		0	5.5	V
Vo	Output Voltage		0	V _{CC}	V
		$V_{CC} = 2V$		-50	uA
I _{OH}	High-level output current	$V_{CC} = 3.3V \pm 0.3V$		-4	mA
		$V_{CC} = 5V \pm 0.5V$		-8	IIIA
		$V_{CC} = 2V$		50	uA
I_{OL}	Low-level output current	$V_{CC} = 5V \pm 0.5V$		4	mA
		$V_{CC} = 3V$		8	IIIA
Δt/ΔV	Input transition rise or fall	$V_{CC} = 3.3V \pm 0.3V$		100	no/\/
ΔυΔν	rate	$V_{CC} = 5V \pm 0.5V$		20	ns/V
T_A	Operating free-air temperature		-40	125	°C

Notes: 3. Unused inputs should be held at V_{CC} or Ground.



Electrical Characteristics

0	Damanatan	To at Oam ditions	V		25°C		-40°C t	o 85°C	-40°C to	o 125ºC	1111
Symbol	Parameter	Test Conditions	V _{CC}	Min	Тур.	Max	Min	Max	Min	Max	Unit
			2V	1.9	2		1.9		1.9		
	High Level	$I_{OH} = -50\mu A$	3V	2.9	3		2.9		2.9		
V _{OH}	Output		4.5V	4.4	4.5		4.4		4.4		V
	Voltage	$I_{OH} = -4mA$	3V	2.58			2.48		2.40		
		$I_{OH} = -8mA$	4.5V	3.94			3.8		3.70		
			2V			0.1		0.1		0.1	
	Low Level	$I_{OL} = 50\mu A$	3V			0.1		0.1		0.1	
V _{OL}	Output		4.5V			0.1		0.1		0.1	V
	Voltage	$I_{OL} = 4mA$	3V			0.36		0.44		0.55	
		$I_{OL} = 8mA$	4.5V			0.36		0.44		0.55	
II	Input Current	V _I = 5.5 V or GND	0 to 5.5V			± 0.1		± 1		± 2	μΑ
l _{OZ}	Z State Leakage Current	V _O =0 to 5.5 V	5.5V			0.25		2.5		10	μΑ
Icc	Supply Current	$V_I = 5.5V$ or GND $I_O=0$	5.5V			1		10		40	μΑ
Cı	Input Capacitance	$V_I = V_{CC} - \text{or GND}$	5.5V		2.0	10		10		10	pF
θ_{JA}	Thermal Resistance	SOT25	(Note 4)		195						°C/W
ОЈД	Junction-to- Ambient	SOT353	(Note 4)		430						C/ VV
Aug	Thermal Resistance SOT25	(Note 4)		58						°C/W	
θ_{JC}	Junction-to- Case	SOT353	(Note 4)		155						C/VV

Note: 4. Test conditions for SOT25, and SOT353: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout



Switching Characteristics

 $V_{CC} = 3.3V \pm 0.3$ (see Figure 1)

Parameter	From	ТО	TO 25°C -40°C to 85°C		25°C		o 85ºC	-40°C to	125ºC	Unit	
Parameter	(Input) (OUTPUT)			Min	Тур.	Max	Min	Max	Min	Max	Ollit
	^	>	C _L =15pF	0.6	4.4	8.0	0.6	9.5	0.6	10.0	ns
t _{pd}	Α	ĭ	C _L =50pF	0.6	6.3	11.5	0.6	13.0	0.6	14.5	ns
	0.	V	C _L =15pF	0.6	4.9	8.0	0.6	9.5	0.6	10.0	ns
t _{en}	OE	ĭ	C _L =50pF	0.6	7.0	11.5	0.6	13.0	0.6	14.5	ns
	OE	V	C _L =15pF	0.6	6.3	9.7	0.6	11.5	0.6	12.5	ns
t _{dis}	OE	Ť	C _L =50pF	0.6	9.0	13.2	0.6	15.0	0.6	16.5	ns

$V_{CC} = 5V \pm 0.5V$ (see Figure 1)

Davamatav	Parameter From TO (Input) (OUTPUT)				25°C -40		-40 °C t	-40 °C to 85 °C		-40 °C to 125 °C	
Parameter				Min	Тур.	Max	Min	Max	Min	Max	Unit
4	^	V	C _L =15pF	0.6	3.4	5.5	0.6	6.5	0.6	7.0	ns
t _{pd}	Α	Ť	C _L =50pF	0.6	4.7	7.5	0.6	8.5	0.6	9.5	ns
	0.5	V	C _L =15pF	0.6	3.6	5.6	0.6	6.3	0.6	7.0	ns
t _{en}	OE	Y	C _L =50pF	0.6	5.4	8.0	0.6	9.0	0.6	9.5	ns
4	OF	V	C _L =15pF	0.6	4.3	6.8	0.6	8.0	0.6	8.5	ns
t _{dis}	OE	Ť	C _L =50pF	0.6	6.1	8.8	0.6	10.0	0.6	11.0	ns

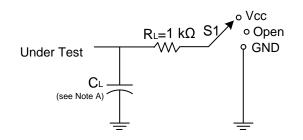
Operating Characteristics

T_A = 25 °C

Parameter		Test Conditions	V _{CC} = 5 V Typ.	Unit
C_{pd}	Power dissipation capacitance	f = 1 MHz No Load	12	pF

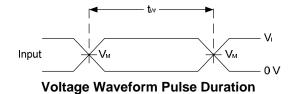


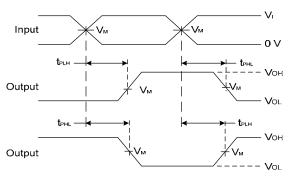
Parameter Measurement Information



TEST	S 1
t _{PLH} /t _{PHL}	Open
t _{PLZ} /t _{PZL}	Vload
t _{PHZ} /t _{PZH}	GND

V	In	puts	V		V/A
V _{CC}	VI	t _r /t _f	V _M	CL	V Δ
3.3V±0.3V	V _{CC}	≤3ns	V _{CC} /2	15pF	0.3V
5V±0.5V	V _{CC}	≤3ns	V _{CC} /2	15pF	0.3V
3.3V±0.3V	V _{CC}	≤3ns	V _{CC} /2	50pF	0.3V
5V±0.5V	V _{CC}	≤3ns	V _{CC} /2	50pF	0.3V





Output Control

Output Waveform 1
S1 at V_{LOAD}
(see Note B)

Output Waveform 2
S1 at GND
(see Note B)

Voltage Waveform Enable and Disable Times
Low and High Level Enabling

Voltage Waveform Propagation Delay Times Inverting and Non Inverting Outputs

Figure 1. Load Circuit and Voltage Waveforms

Notes: A. Includes test lead and test apparatus capacitance.

B. All pulses are supplied at pulse repetition rate ≤ 1 MHz.

C. Inputs are measured separately one transition per measurement.

D. t_{PLZ} and t_{PHZ} are the same as t_{dis.}

E. t_{PZL} and t_{PZH} are the same as t_{EN}.

F. t_{PLH} and t_{PHL} are the same as t_{PD}.



Ordering Information

T4AHC1G 126 XX - 7

Logic Device Function Package Packing

74 : Logic Prefix 126 : 3-State Buffer W5 : SOT25 7 : Tape & Reel

AHC: 2 to 5.5V

Family 1G : One gate

OE -Hign SE : SOT353

	Device	Package	Packaging	7" Tape	and Reel
	Device	Code	(Note 5)	Quantity	Part Number Suffix
3	74AHC1G126W5-7	W5	SOT25	3000/Tape & Reel	-7
2	74AHC1G126SE-7	SF	SOT353	3000/Tape & Reel	-7

Notes: 5. Pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.

Marking Information

(Top View)

XX: Identification code

Y : Year 0~9

 $\underline{\underline{W}}$: Week : A $^{\sim}$ Z : 1 $^{\sim}$ 26 week;

a z : 27 5 2 week; z represents 52 and 53 week

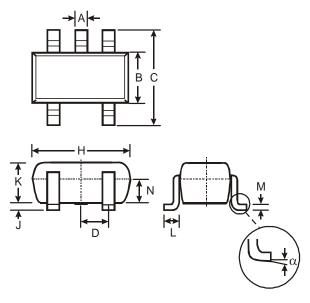
52 and 53 week X: A~Z: Internal code

Part Number	Package	Identification Code
74AHC1G126W5	SOT25	YZ
74AHC1G126SE	SOT353	YZ



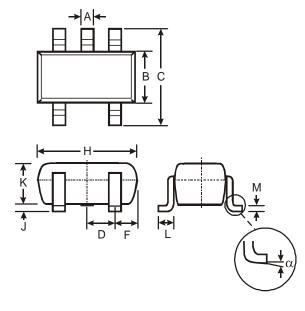
Package Outline Dimensions (All Dimensions in mm)

(1) Package Type: SOT25



SOT25				
Dim	Min	Max	Тур	
A	0.35	0.50	0.38	
В	1.50	1.70	1.60	
O	2.70	3.00	2.80	
D	_	_	0.95	
Н	2.90	3.10	3.00	
7	0.013	0.10	0.05	
K	1.00	1.30	1.10	
L	0.35	0.55	0.40	
M	0.10	0.20	0.15	
N	0.70	0.80	0.75	
α	0°	8°		
All Dimensions in mm				

(2) Package Type: SOT353



SOT353			
Dim	Min	Max	
Α	0.10	0.30	
В	1.15	1.35	
С	2.00	2.20	
D	0.65 Typ		
F	0.40	0.45	
Н	1.80	2.20	
J	0	0.10	
K	0.90	1.00	
L	0.25	0.40	
M	0.10	0.22	
α	0°	8°	
All Dimensions in mm			



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